



IT-8338G

IT-8338G- Next Generation Halogen free product for

- Base Stations, Power amplifiers
- LNBS for Direct Broadcast systems
- Antenna applications
- Dipole antennas

Features

- Thermoset system with 200 °C Tg
- Very low loss ~0.0023 at 10 GHz.
- Halogen Free
- Excellent dimensional stability
- Very stable DK/Df with Temperature
- Ability to use very low profile Copper for reduced insertion loss.
- Highly suitable for Hybrids
- Ability to make high layer count boards
- Full prepreg offering

Data sheet - IT-8338G

Property		Units	IT-8338G	
		Units	DK-3.38	
THERMAL	Thickness		mm	0.504(20 mils)
	Glass Transition Temp (Tg)	DMA	°C	206
		DSC		195
		TMA		185
	Time to Delam (T300)	With Cu	min.	> 60
	Solder Float		min.	> 60
	Solder Dip (PCT@1 hour and 121°C)			> 60
	Thermal Decomposition Temp (5wt%)		°C	425
	CTE: RT-150°C	X-axis	ppm/°C	22.2
	CTE: RT-150°C	Y-axis	ppm/°C	22.5
	CTE:α1	Z - axis	ppm/°C	68
	CTE:α2	Z - axis	ppm/°C	290
CTE	Z - axis	%	3.90	
ELECTRICAL	Thickness			0.504(20 mils)
	Dielectric Constant (Dk)	@2GHz		3.380
		@3GHz		3.380
		@5GHz		3.380
		@10GHz		3.380
	Dielectric Factor (Df)	@2GHz		0.0023
		@3GHz		0.0023
		@5GHz		0.0023
@10GHz		0.0023		
PHYSICAL	Water Absorption		%	0.23
	Peel Strength	1 oz (HVLP)	lb/in	>4.0
	Flammability	-	Second	V0
	Thermal Conductivity		W/(m×°C)	0.46
	Elastic modulus	X-axis	GPa	12.20
Y-axis		GPa	12.30	